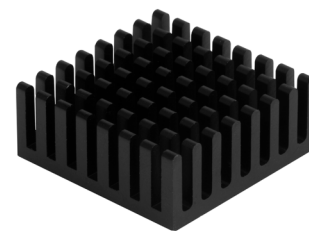


MODEL: HSB24-252510 | **DESCRIPTION:** HEAT SINK**FEATURES**

- BGA design
- small footprint
- top mount
- aluminum alloy

**MODEL**

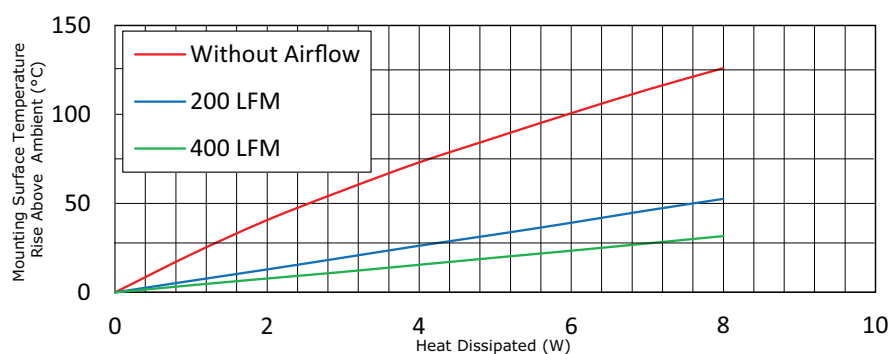
	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
HSB24-252510	18.10	21.3	6.5	4.0	4.14

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	21.3	6.5	4.0
2	40.6	12.9	7.8
3	57.3	19.5	11.5
4	73.0	26.2	15.5
5	86.9	32.5	19.5
6	100.6	39.1	23.4
7	113.8	46.0	27.5
8	125.9	52.5	31.6

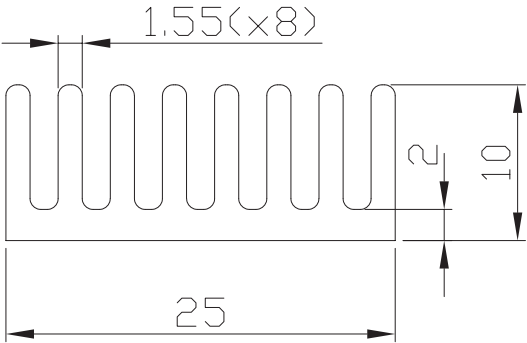
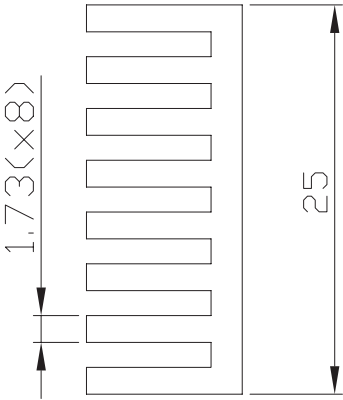
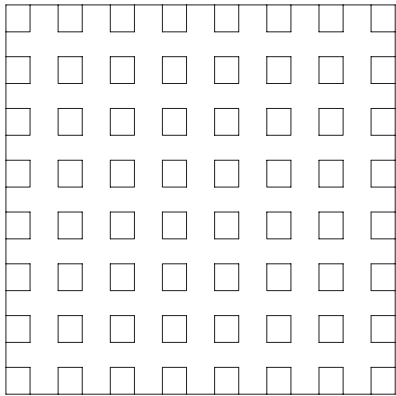
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	8.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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